

# Series UP10 for TO-3 Dual Mount Applications

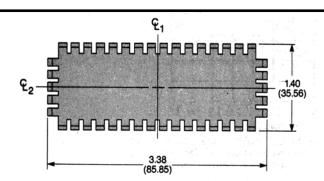
## Technical Data

# METAL CASE, CASE-MOUNTED SEMICONDUCTORS

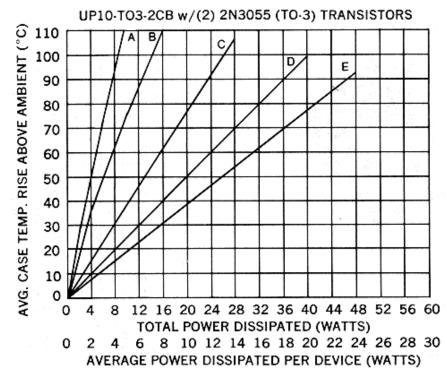
UP10 Series for TO-3 Dual Mount Applications

Natural Conv. (°C/W): 7.7 Forced Air (°C/W): 2

Mounting Envelope: 3.38" x 1.40" x .44"







## Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.

Derate 0.8 °C/watt per device for unplated part in natural convection only.

#### **DESCRIPTION OF CURVES**

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

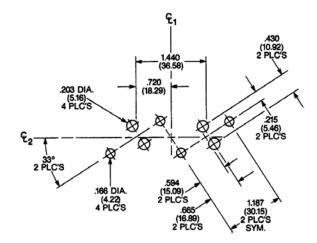
**Ordering Information** 

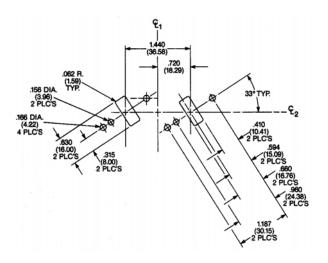
CTS IERC PART NO.			Semiconductor	Hole	Max. Weight
Unplated	Comm'l. Black	Mil. Black	Accommodated	patt. ref.	(Grams)
	Anodize	Anodize		no.	
UP10-TO3-2U	UP10-TO-3-2CB	UP10-TO3-2B	Two TO-3s	29	24.0
UP10-426-2U	UP10-426-2CB	UP10-426-2B	Universal	30	24.0
UP10-428-2U	UP10-428-2CB	UP10-428-2B	Two TO-3 (4-pin)	36	24.0

### **HOLE PATTERNS**

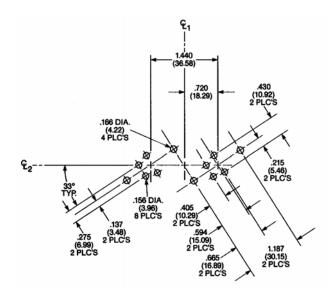
**29.** Hole pattern no. 222 accommodates TO-3s. Available in UP10 series heat dissipators only.

**30.** Hole pattern no. 426 (Universal) accommodates two TO-3s, TO-66s, TO-126s, TO-127s, or TO-220s. Available in UP10 series heat dissipators only.





**36.** Hole pattern no. 428 accommodates two TO-3s (4-pin). Available in UP10 series heat dissipators only.



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